

# Rapid Thermal Process System



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## Specification

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### Chamber



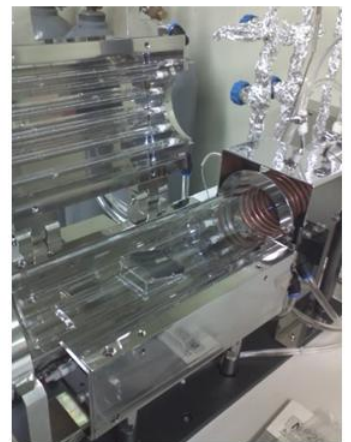
Main Body : Rectangular Type

Material : SUS 304

Loading Chamber : Optional

Chamber inside water cooling

Top side quartz plate



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## Specification

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### Vacuum pump

Rotary pump (Optional : Dry pump)

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Vacuum or Atmospheric Process available

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### Heating unit

Sample Size : Piece ~ 8" Wafer (Etc Optional)

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Heating element : Halogen lamp (Bar type)

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Lamp array : Single or cross array type

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Multi heating zone : 3 zone or multi zone

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Temperature control : T.C or Pyro meter

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SiC edge ring susceptor

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Side process gas injection & exhaust type

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Process gas : Ar, O<sub>2</sub>, N<sub>2</sub>, H<sub>2</sub>

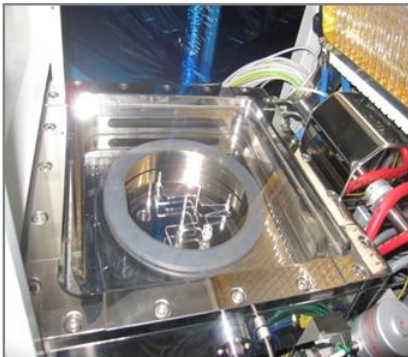
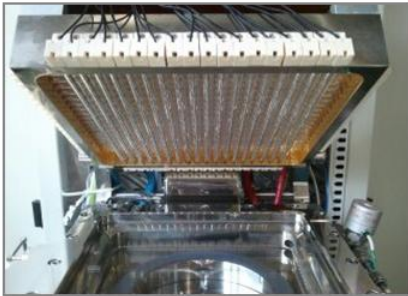
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Easy sample loading

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Easy maintenance

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## Specification

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### Required Services

Main Power : 220V or 380V, 3 Phase, 75A

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PCW (Water) : 2~3kgf/Cm<sup>2</sup>

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Compressed Air : 5.5~6 Kgf/Cm<sup>2</sup>

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N2 Gas (Chamber Vent) : 1~2 Kgf/Cm<sup>2</sup>

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Exhaust : Ø40 sus line (High temp exhaust)

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### Remark

Temperature uniformity : < 2.5%, 1 Sigma (WIW, WTW, RTR)

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Temperature fast ramping rate : > 150°C /Sec

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Temperature control repeatability : < ±5°C

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Wide process temperature range  
: 400°C ~ 1000°C

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Process run time : Within 20 minute at air condition

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Pressure environment : A.T.M or Vacuum

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System Operating Type

Semi-Auto or Fully auto Control

(Using PLC Base Touch screen or P.C Monitor)

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Training

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Warranty : 1 Year (Exclude consumables parts)

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